

Heat dissipating case

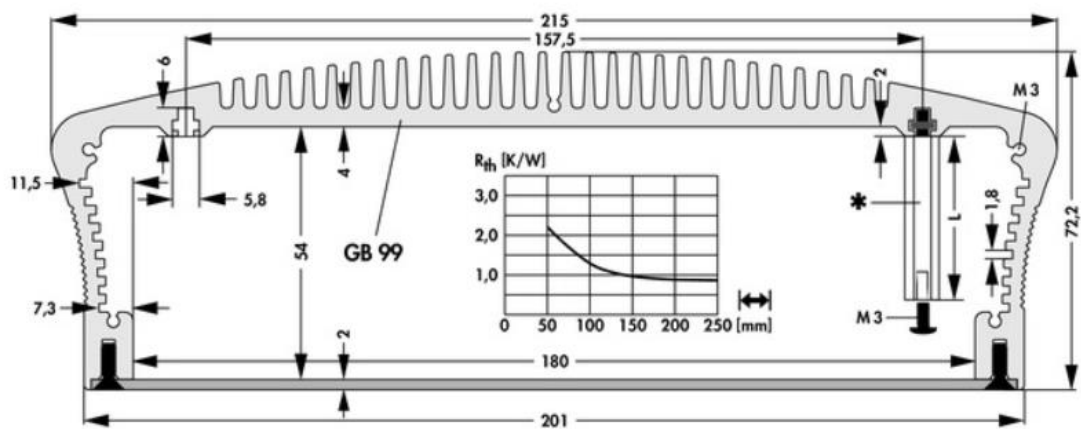
EMB215

EMB 215 250 MS KL BL

Embedded case

universal cooling fin case made of aluminium extruded profile, cover panels in 2 mm thickness and removable bottom panel
optimized heat dissipation by means of external cooling fins
the integrated T-grooves in the case profile for mounting of i.e. mainboards in the Mini-ITX or NUC form factor by means of distance, bolts and mounting plate also EBX, Nano ITX, EPIC, ETX/XTX and PC/104 form factors by means
internal guide grooves for inserting PCBs or mounting plates
wall-, ceiling- or top-hat rail mounting by means of fixing straps or top-hat rail mounting from the bottom
special designs, embedded cover panels, machinings, surfaces and printings upon request
Contents of delivery: 1 = case profile; 2 = cover panel; 3 = 1 x bottom panel; 4 = mounting material

* accessories mounting set BFS



length 250
C
[mm]

